

IN THE CLAIMS:

1. (Allowed) A method of rinsing a wafer comprising:
spinning a wafer;
exposing said spinning wafer to DI water while providing sonic waves to substantially the entire surface area of the wafer; and
after exposing said spinning wafer to DI water, exposing said spinning wafer to a liquid or vapor having a lower surface tension than water.
2. (Allowed) The method of claim 1 wherein said liquid is or vapor comprises isopropyl alcohol (IPA).
3. (Allowed) The method of claim 1 wherein said sonic waves are applied to the backside of said wafer.
4. (Allowed) The method of claim 1 further comprising the step of heating said DI water to a temperature greater than room temperature prior to exposing said spinning wafer to said DI water.
5. (Allowed) The method of claim 1 wherein said wafer is spun at a rate between 50-1000 rpms while exposing said wafer to said DI water and to said liquid or vapor.

6. (Currently Amended) The method of claim 2 wherein the time of exposure to said liquid or vapor is less than the time of exposure to said DI water ~~or vapor~~.

34. (Allowed) A method of rinsing a wafer comprising:
spinning a wafer;
exposing said spinning wafer to water while providing sonic waves to substantially the entire surface area of the wafer; and
after exposing said spinning wafer to water, exposing said spinning wafer to a liquid or vapor having a lower surface tension than water.

35. (Allowed) The method of claim 34 wherein said liquid or vapor comprises isopropyl alcohol (IPA).

36. (Allowed) The method of claim 34 wherein said sonic waves are applied to the backside of said wafer.

37. (Currently Amended) The method of claim 34 further comprising the step of heating said ~~DI~~ water to a temperature greater than room temperature prior to exposing said spinning wafer to said water.

38. (Allowed) The method of claim 34 wherein said wafer is spun at a rate between 50-1000 rpms while exposing said wafer to said water and to said liquid or vapor.

39. (Currently Amended) The method of claim 35 wherein the time of exposure to said liquid or vapor is less the than time of exposure to said water or vapor.

Invitation for a telephone interview

The Examiner is requested to call the undersigned at (408) 720-8300 if there remains any issue with allowance of this case.

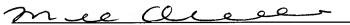
Charge our Deposit Account

Please charge any shortage to our Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN

Date: 1/20/05


Michael A. Bernadicou
Reg. No. 35,934

Patent Counsel
Legal Affairs Dept.
APPLIED MATERIALS, INC.
P.O. Box 450A
Santa Clara, CA 95052

Telephone inquiries to:
Michael A. Bernadicou
(408) 720-8300